

IN THE CLAIMS:

Cancel claims 2, 5, 10, 13, 18, and 21.

Please amend the claims as follows:

1. (Currently Amended) A laser-markable structure for marking a semiconductor device comprising:
a tape comprising a flexible film material; and
a multilayer adhesive including:
a first outermost adhesive layer comprising a mixture of electromagnetic radiation-curable components, the electromagnetic radiation-curable components providing a laser-markable surface upon exposure to an electromagnetic radiation source by curing and bonding to at least a portion of a semiconductor device; and
a second adhesive layer disposed between the tape and the first outermost adhesive layer, the second adhesive layer comprising a mixture of electromagnetic radiation-curable components so that when exposed to radiation the second adhesive layer performs at least one of curing onto portions of the first outermost adhesive layer or ~~and~~ losing adhesive properties for facilitating peeling of the flexible film material from at least a portion of a surface of a semiconductor device.
2. (Canceled)
3. (Currently Amended) The laser-markable structure of claim 1 ~~2~~, wherein the at least a portion of the surface of a bare semiconductor device ~~die~~ has grinding marks therein.
4. (Currently Amended) The laser-markable structure of claim 1 ~~2~~, wherein the first outermost adhesive layer is permanently attached to the at least a portion of the surface of the bare semiconductor device ~~die~~ when the radiation-curable components are in a cured state.

5. (Canceled)

6. (Previously Presented) The laser-markable structure of claim 4, wherein the laser-markable surface includes a substantially homogenous surface disposed over the at least a portion of the surface of the bare semiconductor die, the laser-markable surface being suitable for laser marking.

7. (Previously Presented) The laser-markable structure of claim 3, wherein the second adhesive layer comprises radiation-curable components.

8. (Previously Presented) The laser-markable structure of claim 1, wherein the tape comprises a flexible film material having translucent properties.

9. (Currently Amended) A tape for use in the laser marking of a semiconductor device comprising:

a flexible film material; and

a multilayer adhesive including:

a first outermost adhesive layer comprising a mixture of electromagnetic radiation-curable components for providing a mark on a laser-markable surface upon exposure thereof to electromagnetic radiation by curing and bonding to at least a portion of a semiconductor device; and

a second adhesive layer disposed between the flexible film material and the first outermost adhesive layer, the second adhesive layer comprising a mixture of electromagnetic radiation-curable components so that when exposed to radiation the second adhesive layer performs at least one of curing onto portions of the first outermost adhesive layer or ~~and~~ losing adhesive properties for facilitating peeling of the flexible film material from at least a portion of a surface of a semiconductor device.

10. (Canceled)

11. (Currently Amended) The tape of claim 9 ~~10~~, wherein the portion of the surface of the ~~bare~~ semiconductor device ~~die~~ has grinding marks therein.

12. (Currently Amended) The tape of claim 9 ~~10~~, wherein the first outermost adhesive layer is permanently attached to the at least a portion of the surface of the bare semiconductor die when the radiation-curable components are in a cured state.

13. (Canceled)

14. (Previously Presented) The tape of claim 12, wherein the laser-markable surface comprises a substantially homogenous surface disposed over the at least a portion of the surface of the bare semiconductor die suitable for providing a mark by laser marking.

15. (Previously Presented) The tape of claim 11, wherein the second adhesive layer comprises radiation-curable components.

16. (Previously Presented) The tape of claim 9, wherein the flexible film material comprises a flexible film material having translucent properties.

17. (Currently Amended) A tape for use in the marking of a semiconductor device comprising:

film material; and

at least two layers of adhesive including:

- a first outermost adhesive layer comprising a mixture of electromagnetic radiation-curable components for providing a mark on a surface upon exposure thereof to electromagnetic radiation by curing and bonding to at least a portion of a semiconductor device; and
- a second adhesive layer disposed between the film material and the first outermost adhesive layer, the second adhesive layer comprising a mixture of electromagnetic radiation-curable components so that when exposed to radiation the second adhesive layer performs at least one of curing onto portions of the first outermost adhesive layer or ~~and~~-losing adhesive properties for facilitating peeling of the flexible film material from at least a portion of a surface of a semiconductor device.

18. (Canceled)

19. (Currently Amended) The tape of claim 17 ~~18~~, wherein the portion of the surface of the ~~bare~~ semiconductor device ~~die~~ has grinding marks therein.

20. (Currently Amended) The tape of claim 17 ~~18~~, wherein the first outermost adhesive layer is permanently attached to the at least a portion of the surface of the bare semiconductor die when the radiation-curable components are in a cured state.

21. (Canceled)

22. (Previously Presented) The tape of claim 20, wherein the electromagnetic radiation-curable components form a substantially homogenous surface upon exposure to an electromagnetic radiation source, the substantially homogenous surface being disposed over the at least the portion of the surface of a bare semiconductor die, the substantially homogenous surface being suitable for laser marking for forming a mark on the surface of the bare semiconductor die.

23. (Previously Presented) The tape of claim 19, wherein the second adhesive layer comprises electromagnetic radiation-curable components.

24. (Previously Presented) The tape of claim 17, wherein the film material comprises a film material having translucent properties.